

FIG. 1

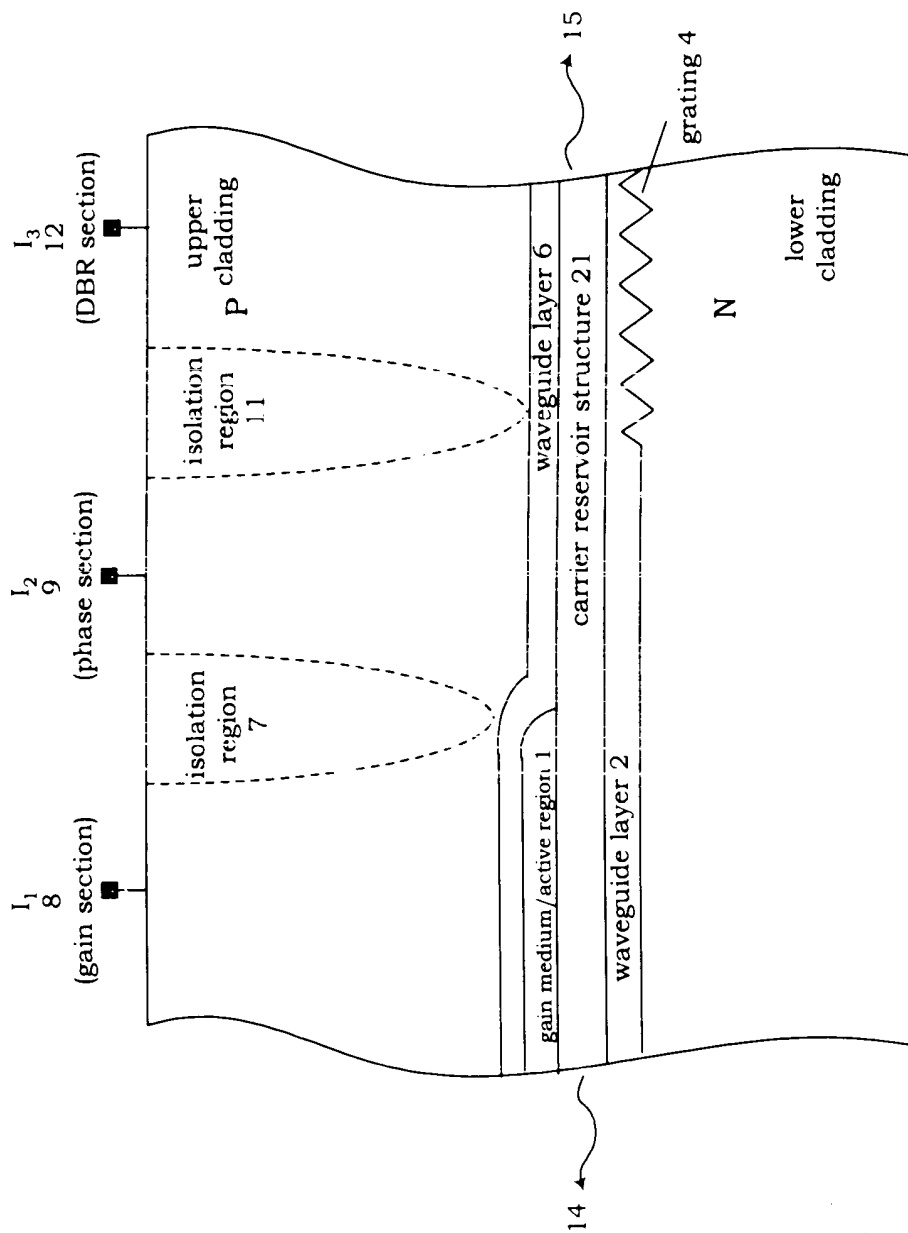


FIG. 2

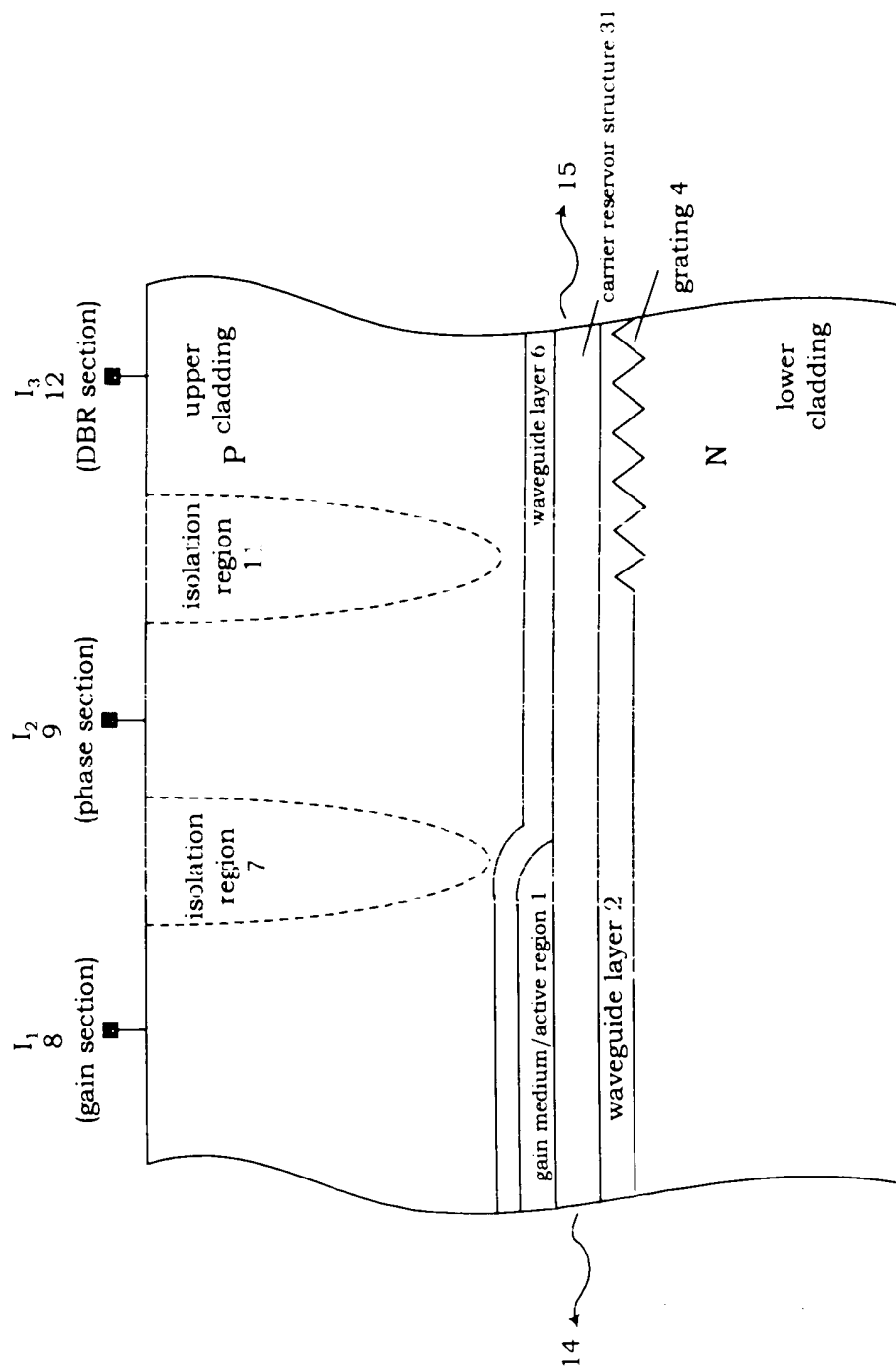


FIG. 3

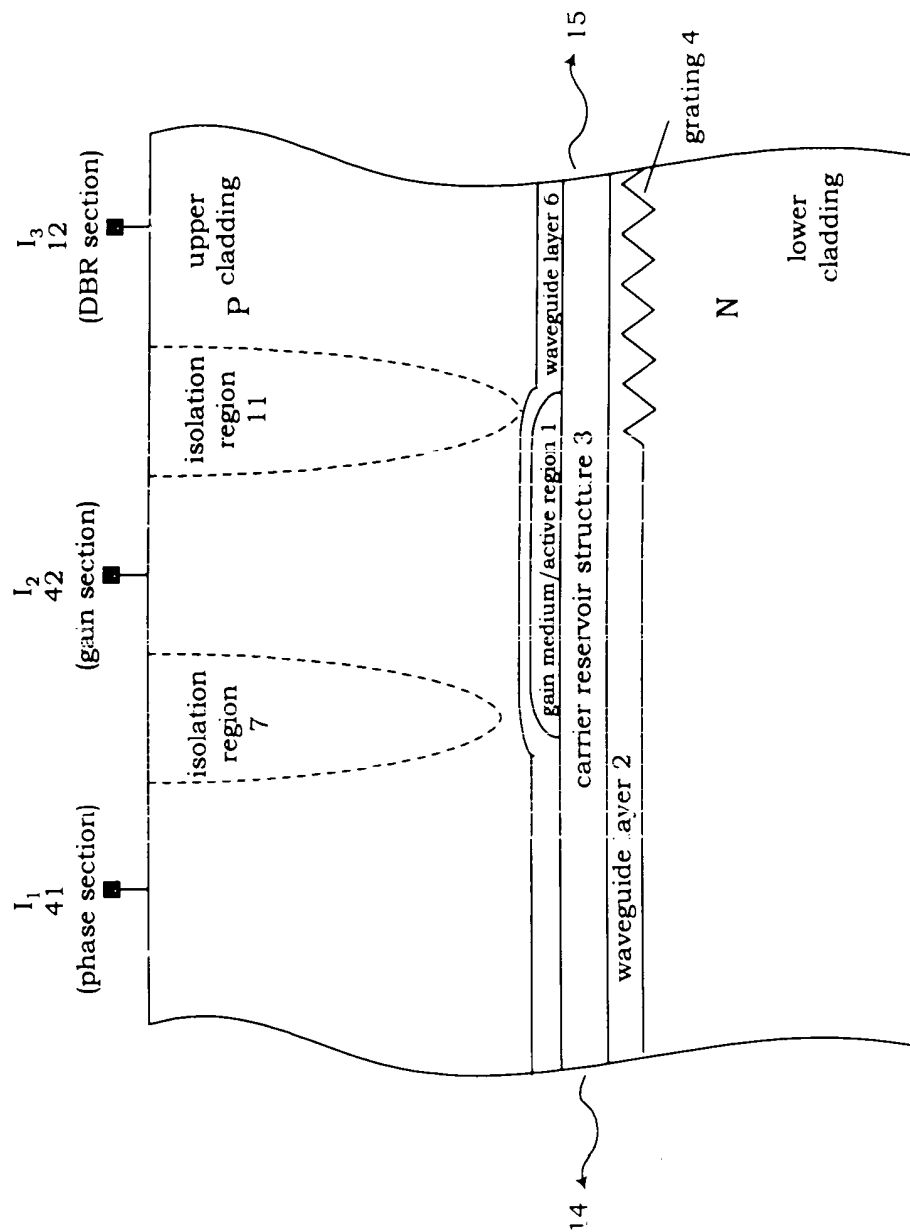


FIG. 4

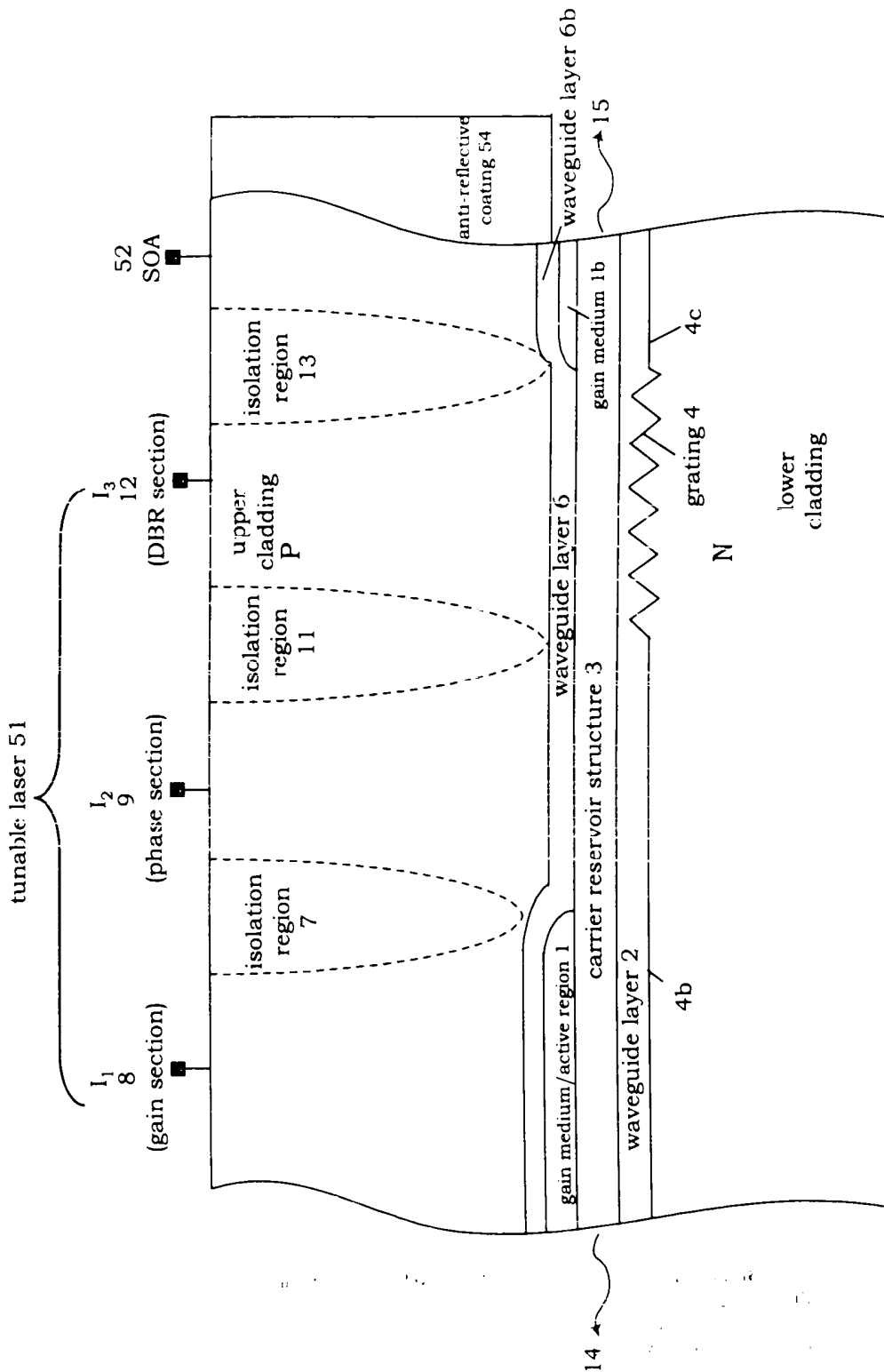
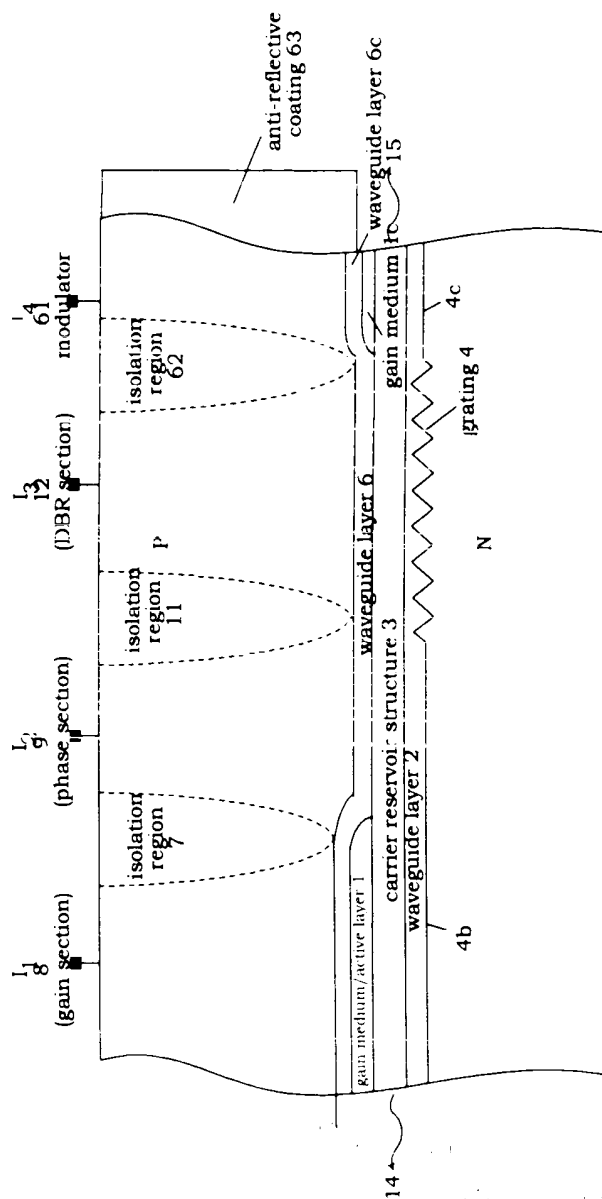
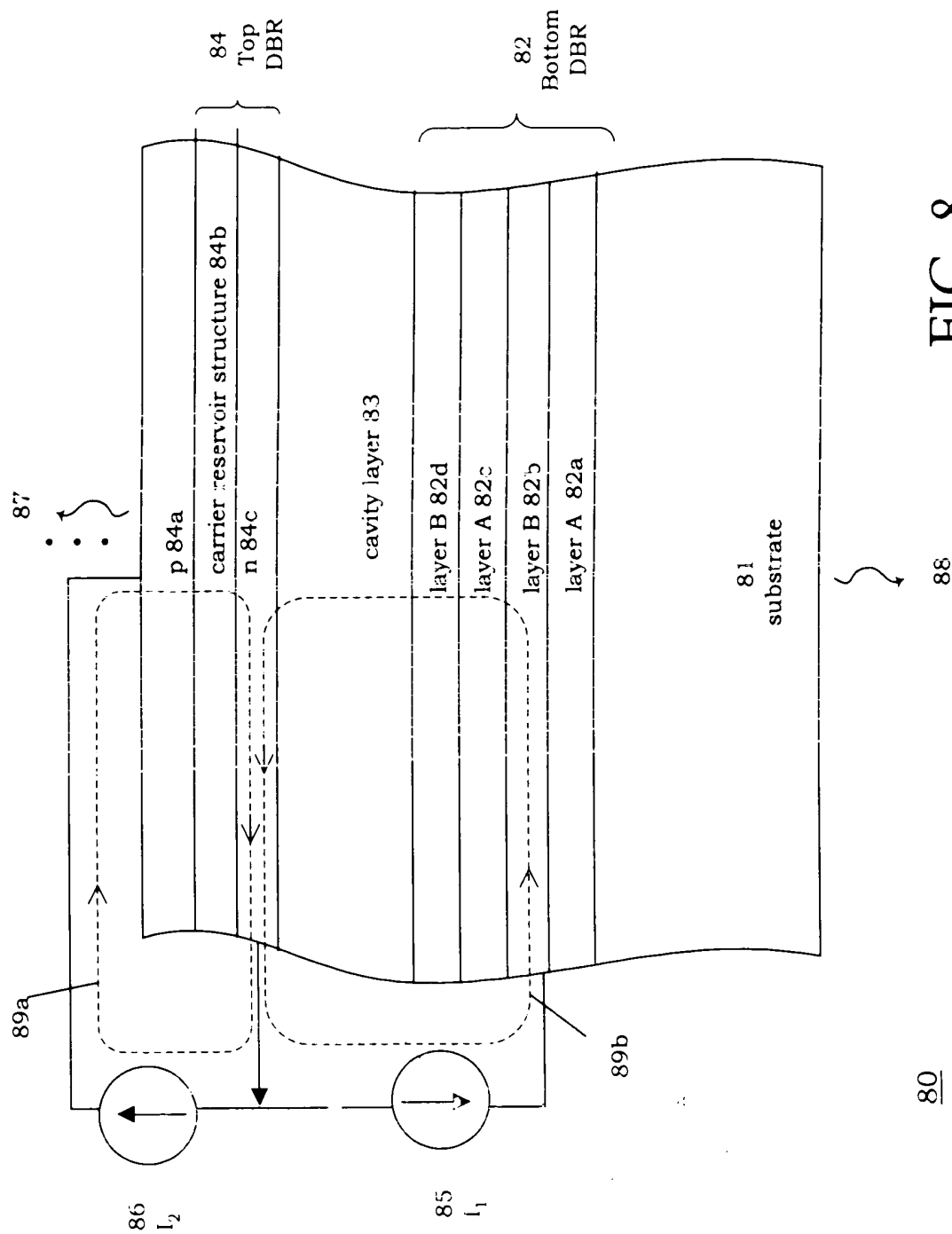


FIG. 5



60

FIG. 6



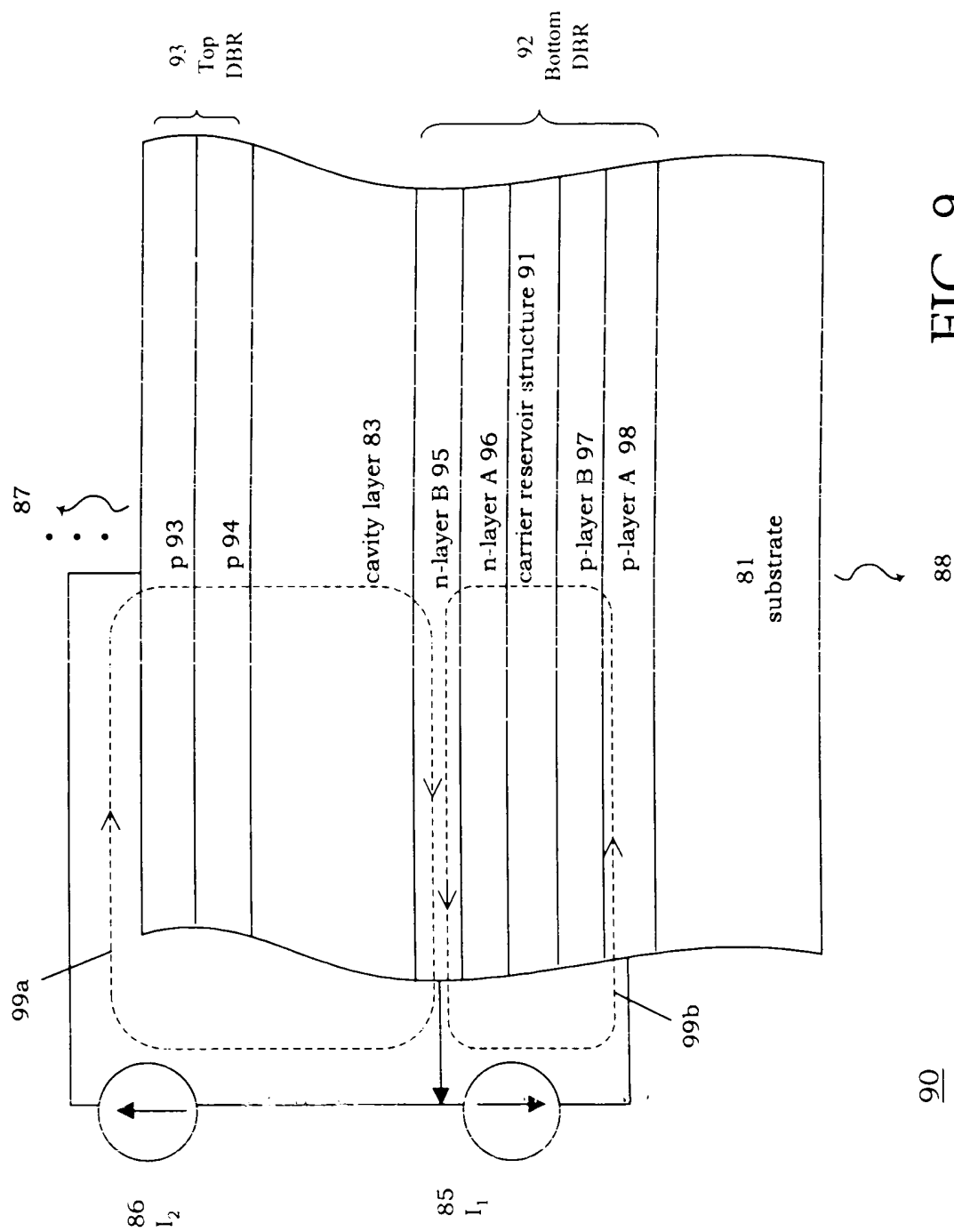


FIG. 9

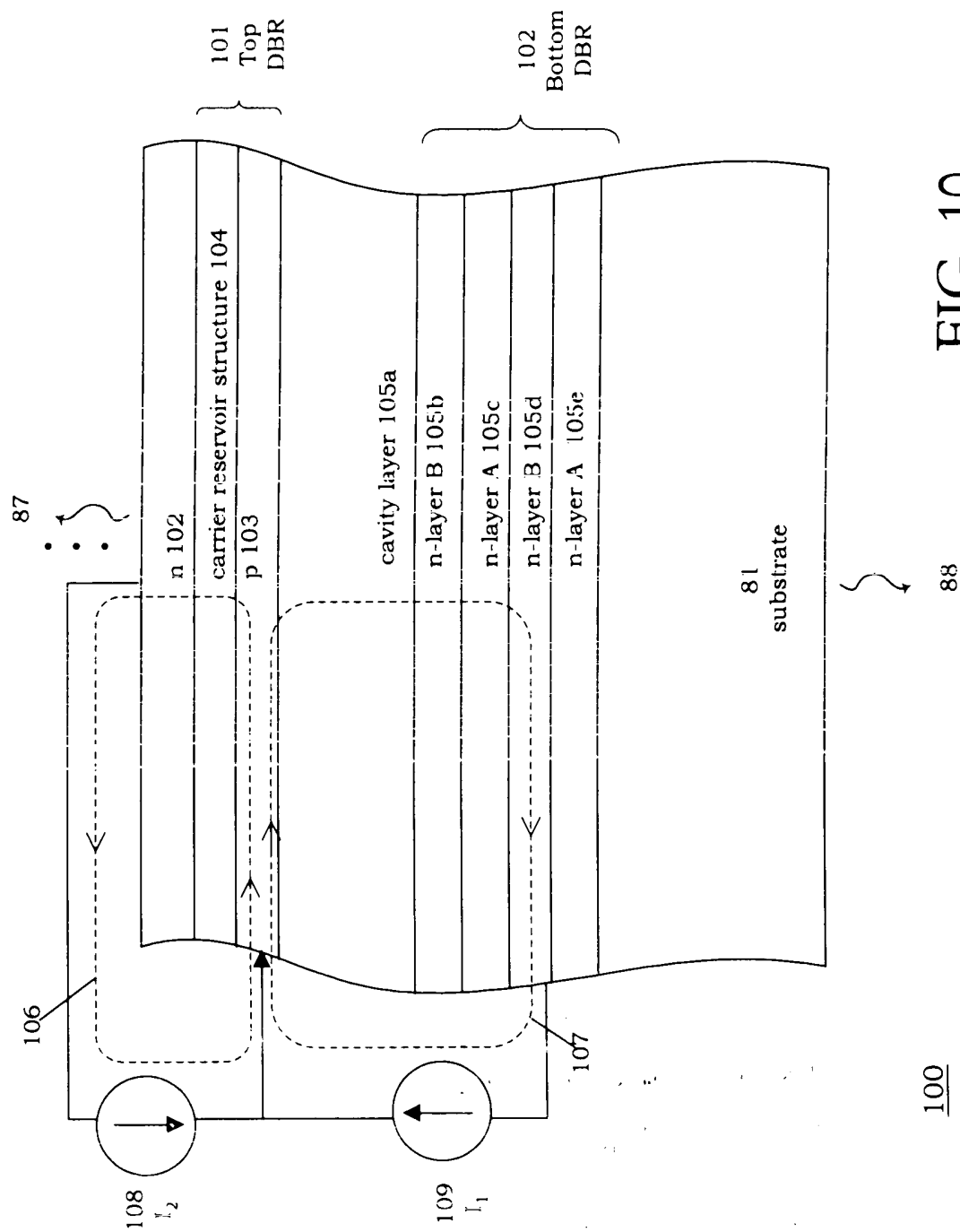


FIG. 10

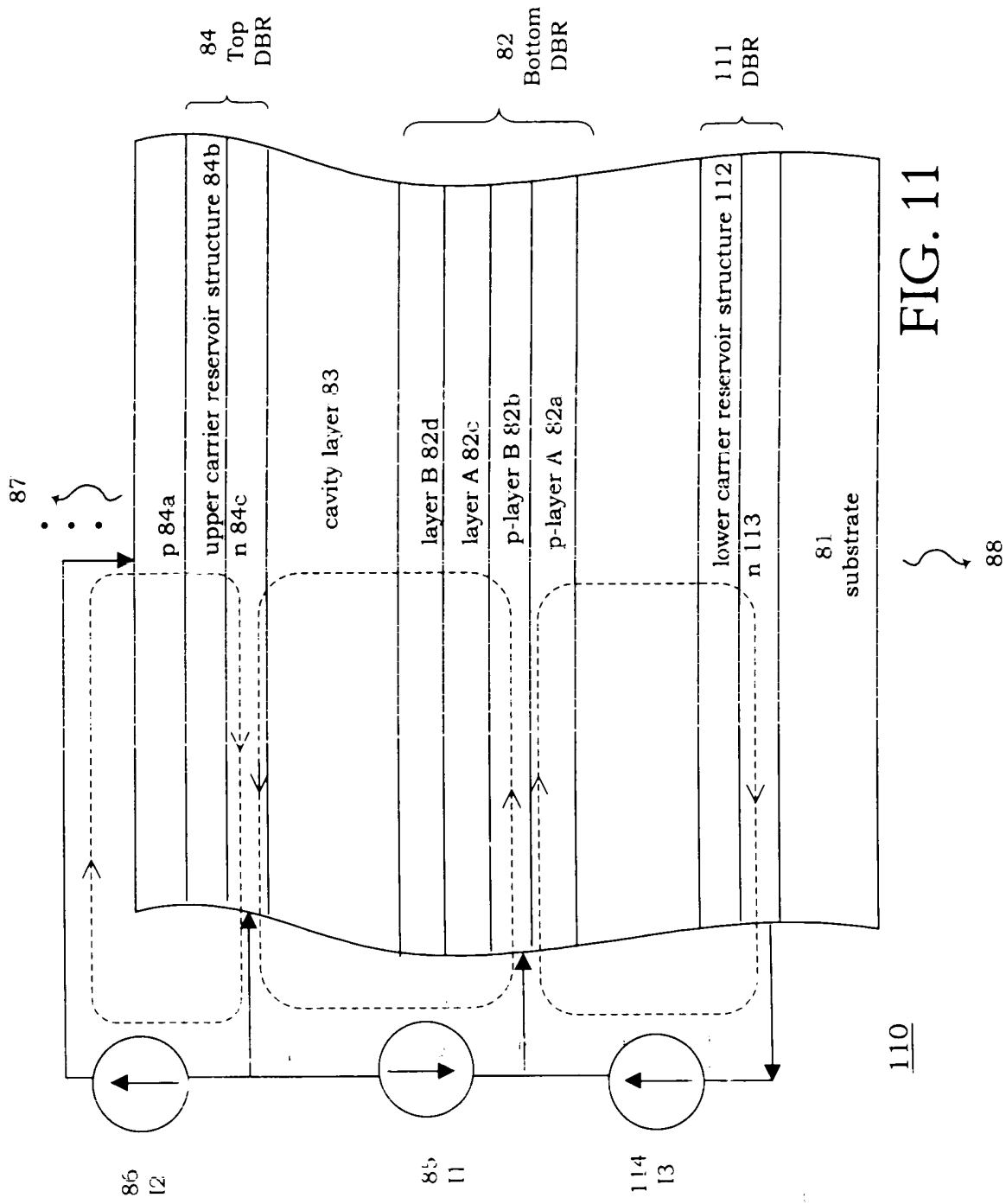
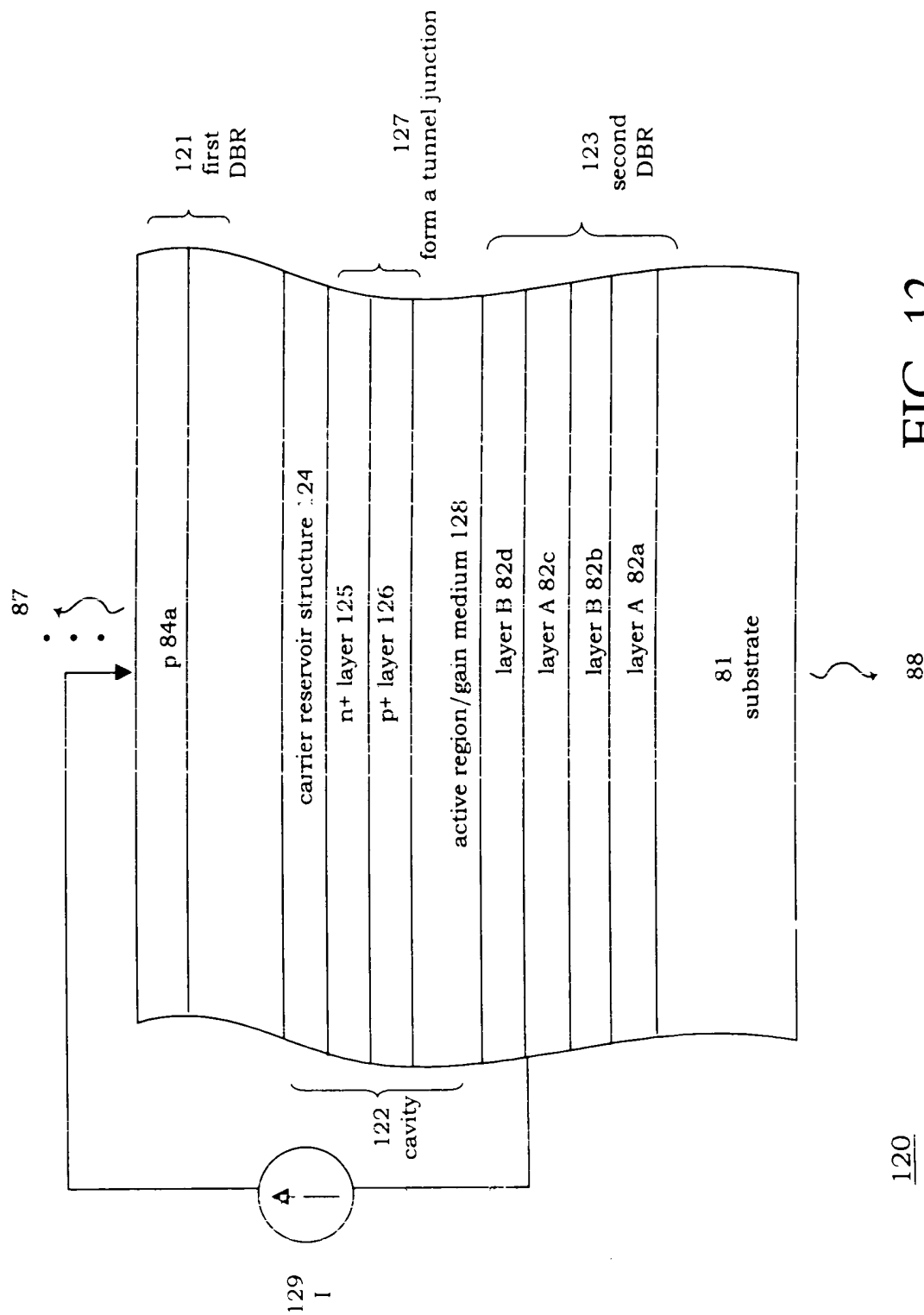


FIG. 11



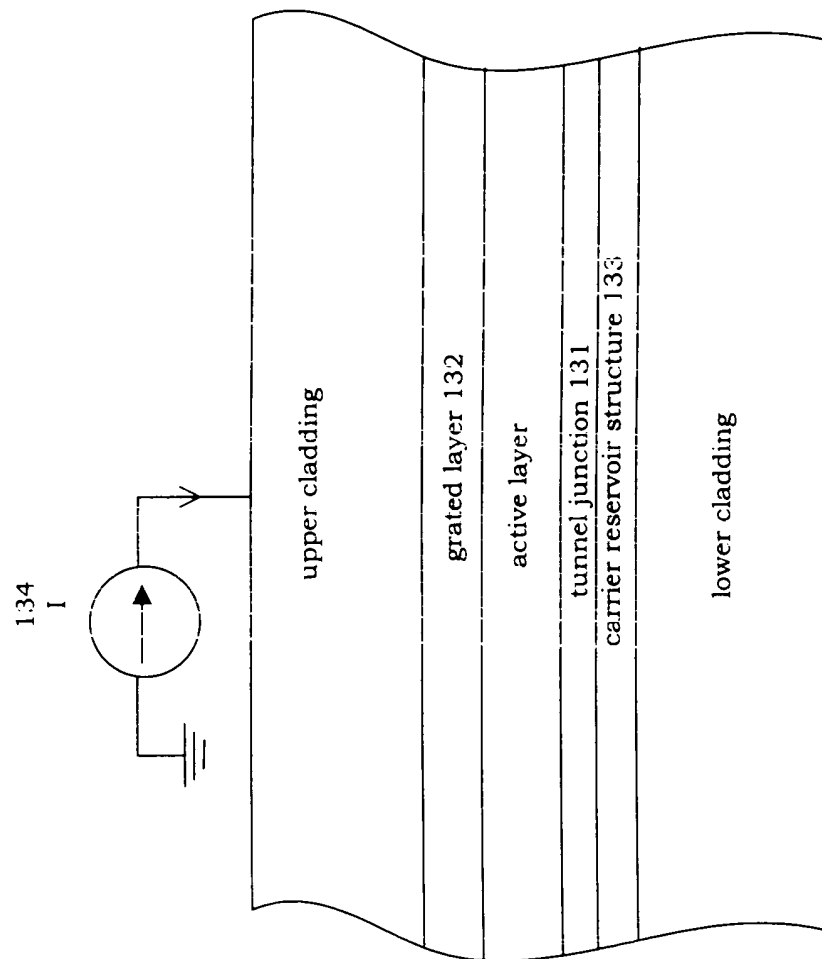


FIG. 13

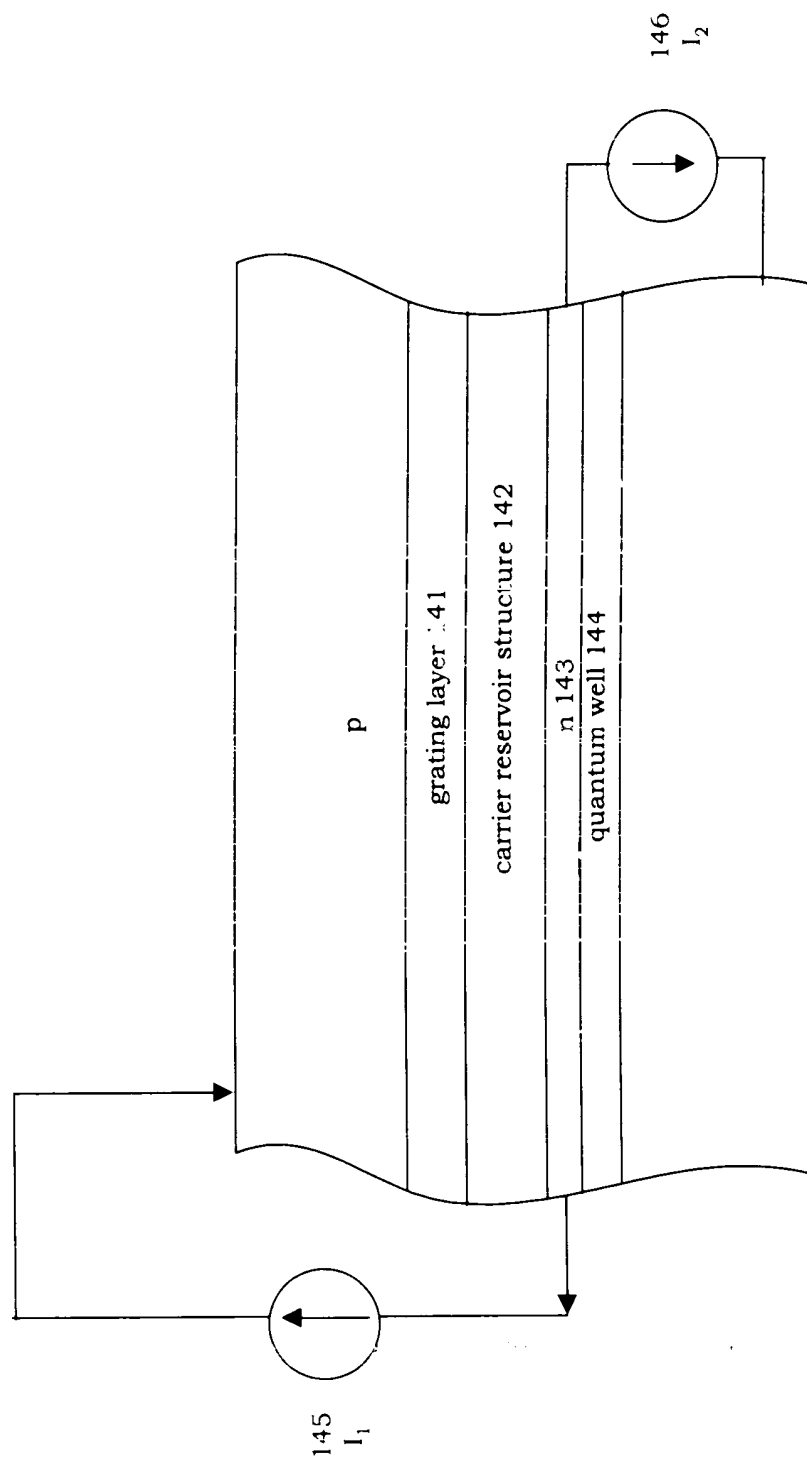


FIG. 14

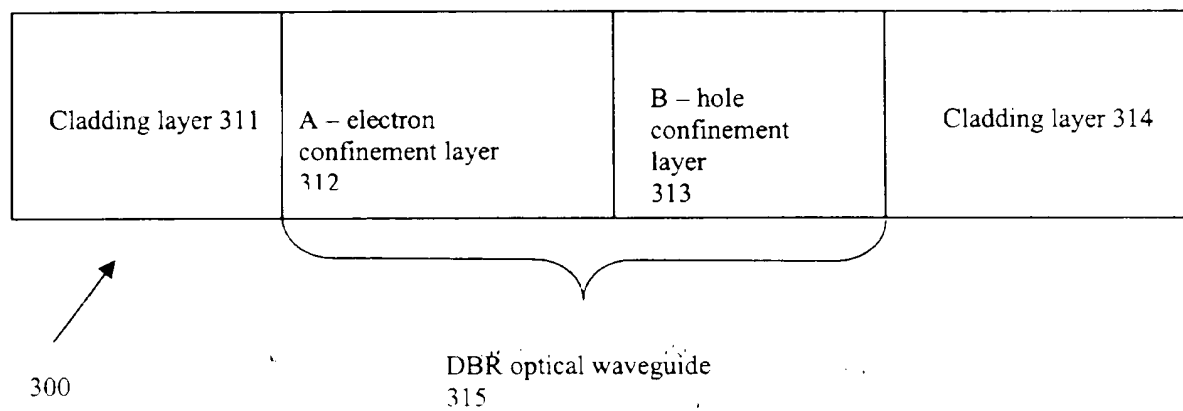
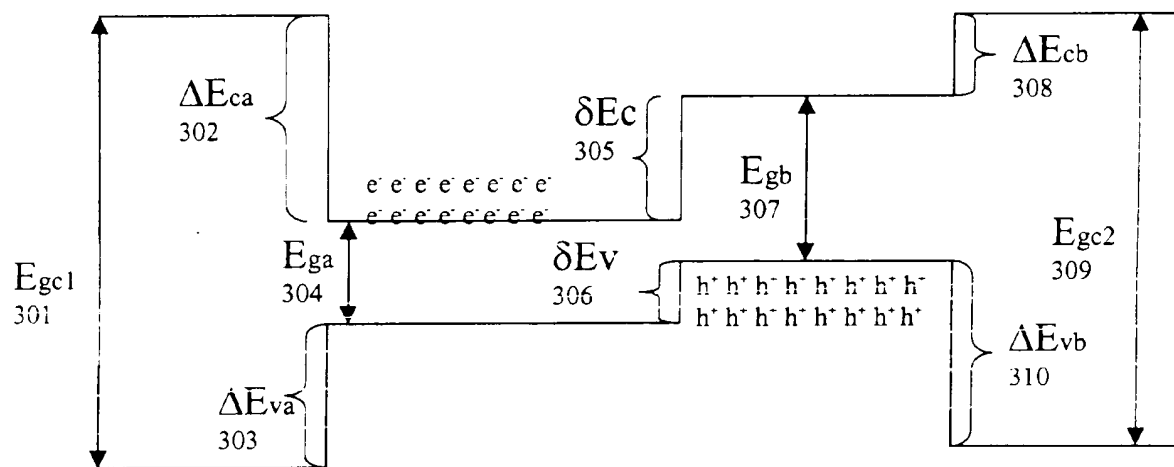
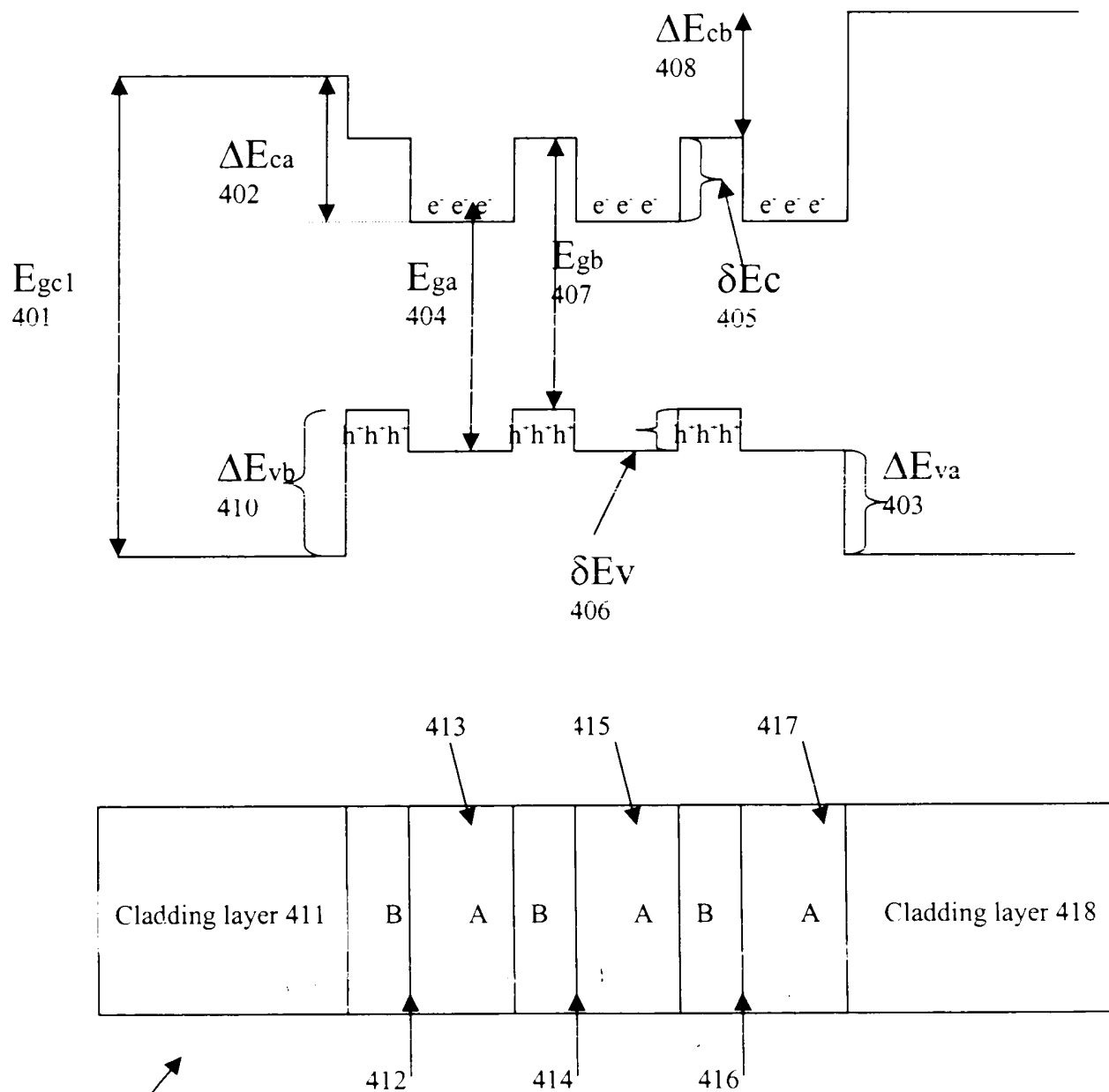


FIG. 15



400

A= electron confinement layer
B= hole confinement layer

FIG.16

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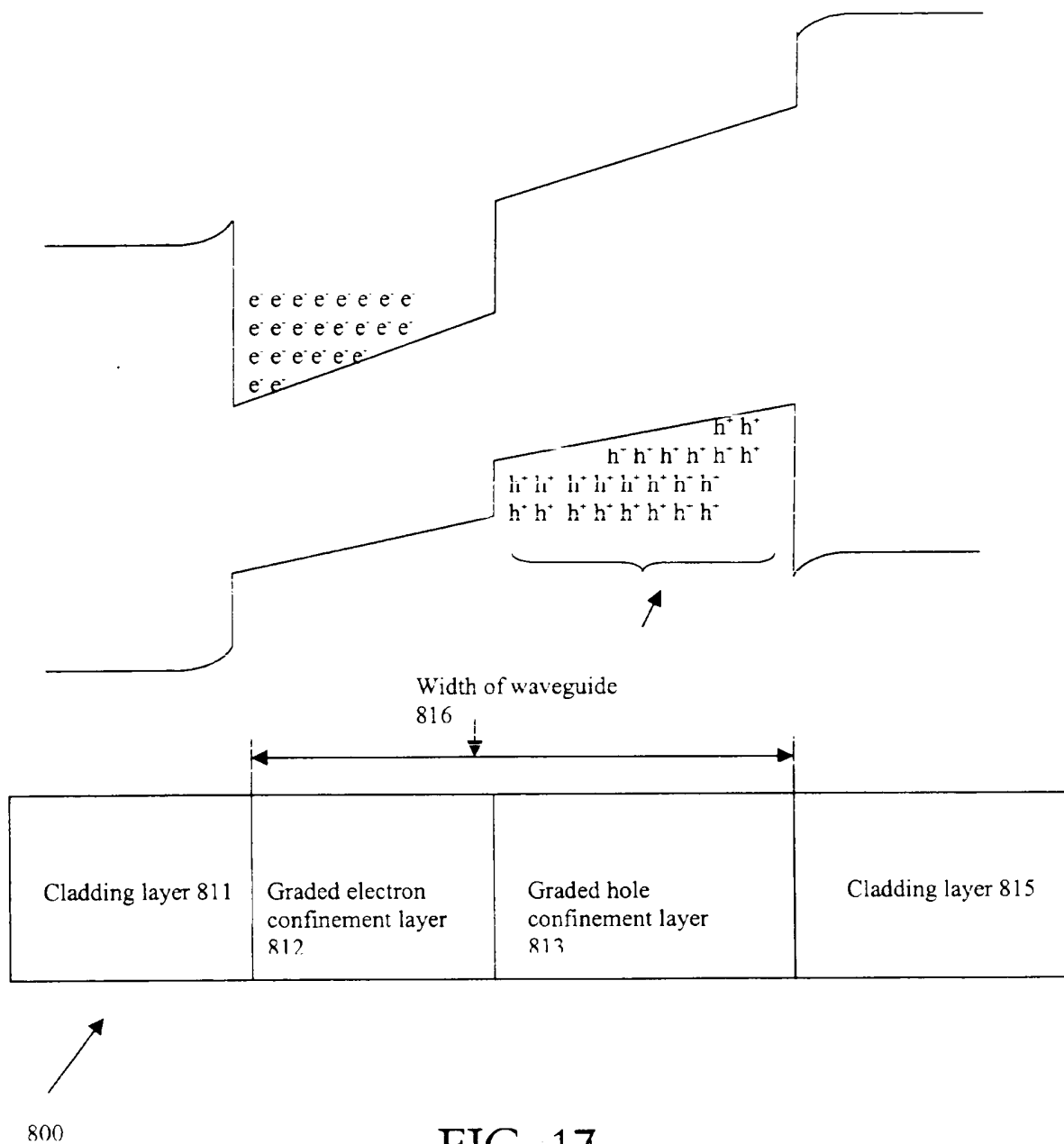


FIG. 17

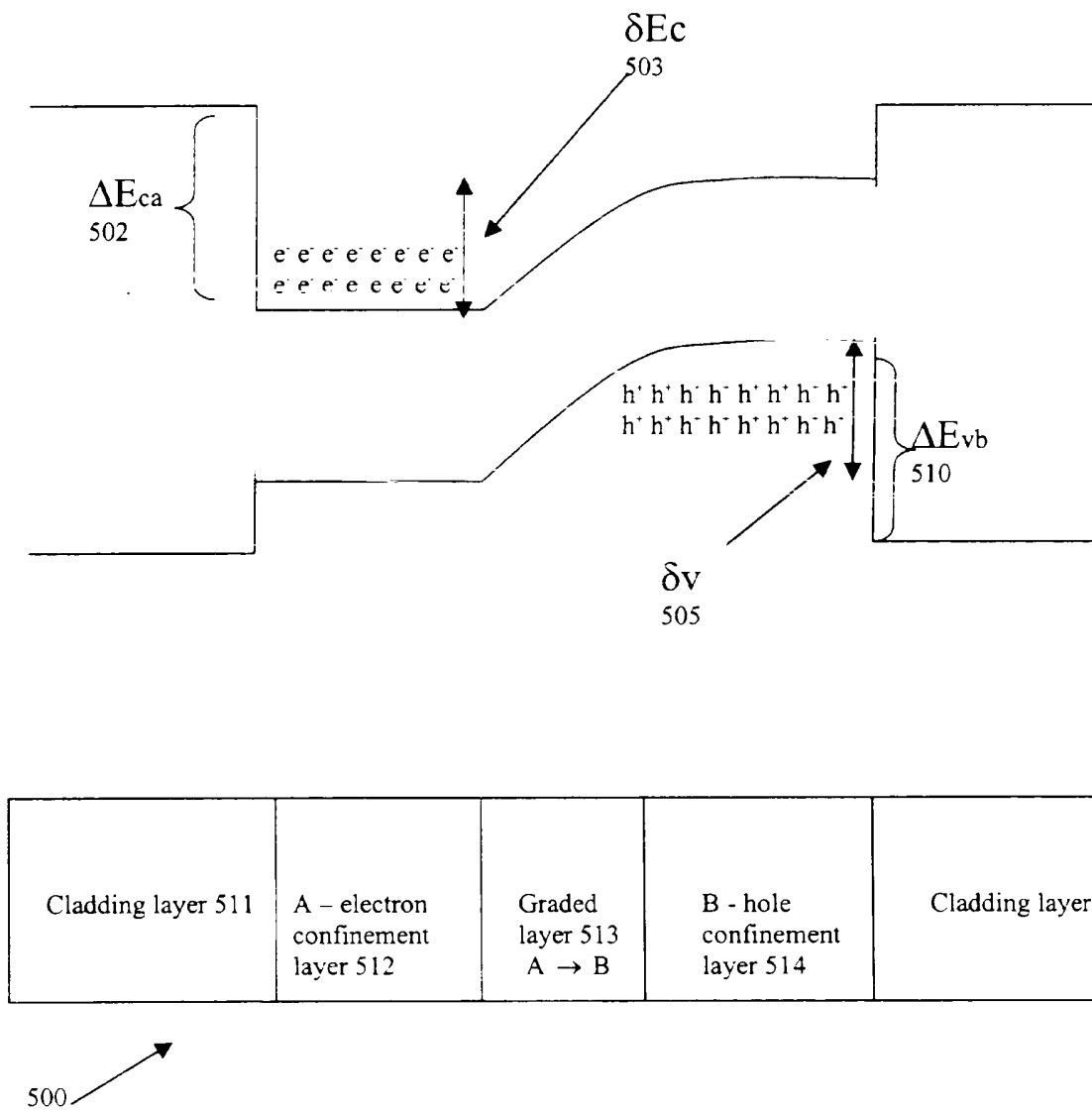


FIG. 18

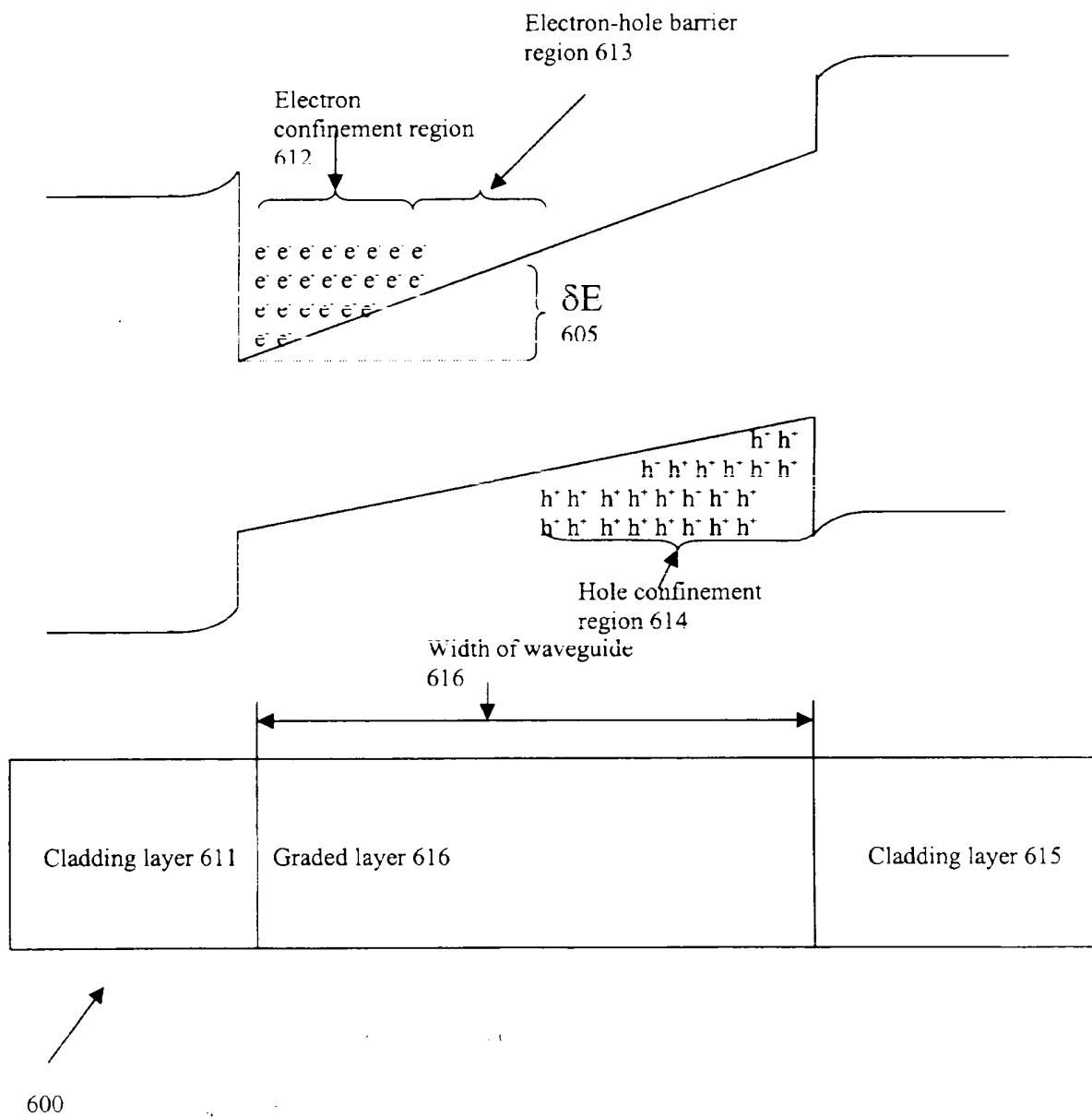


FIG. 19

FIG. 20

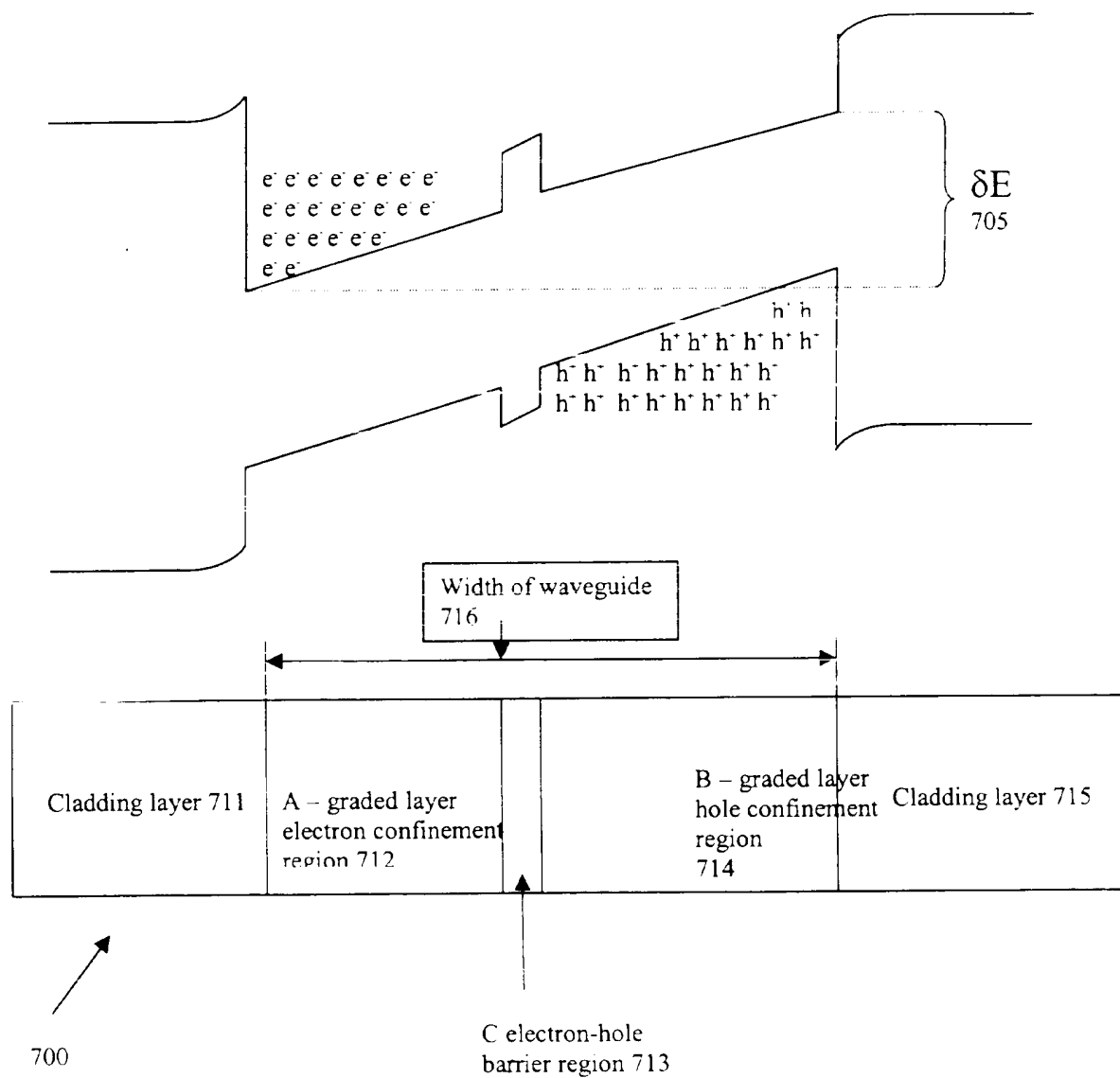


FIG. 20

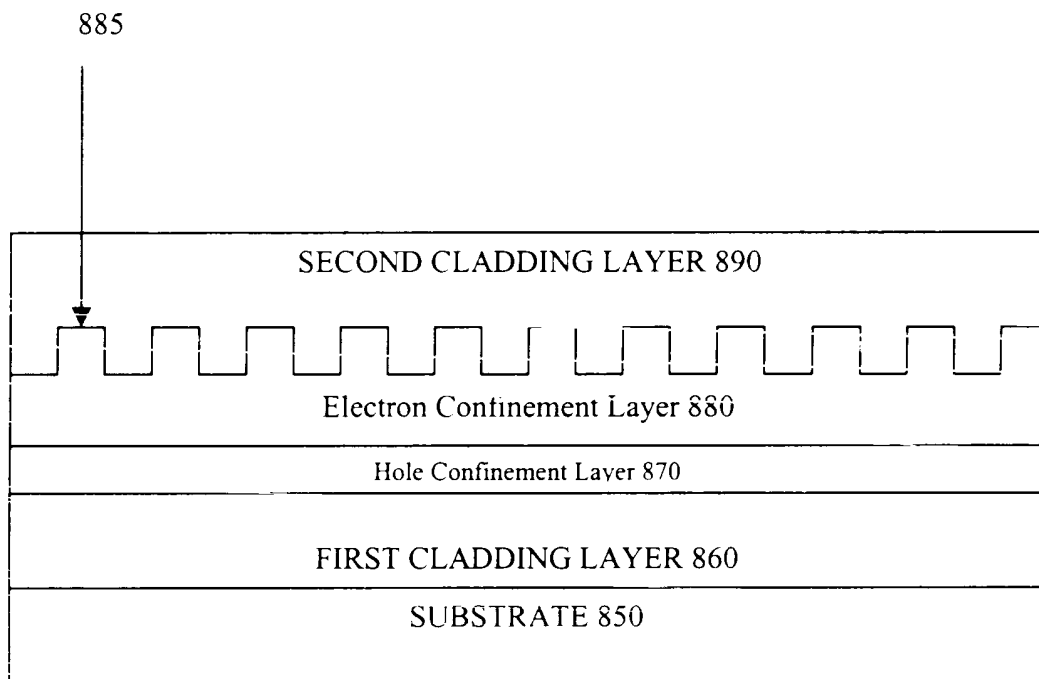


FIG. 21

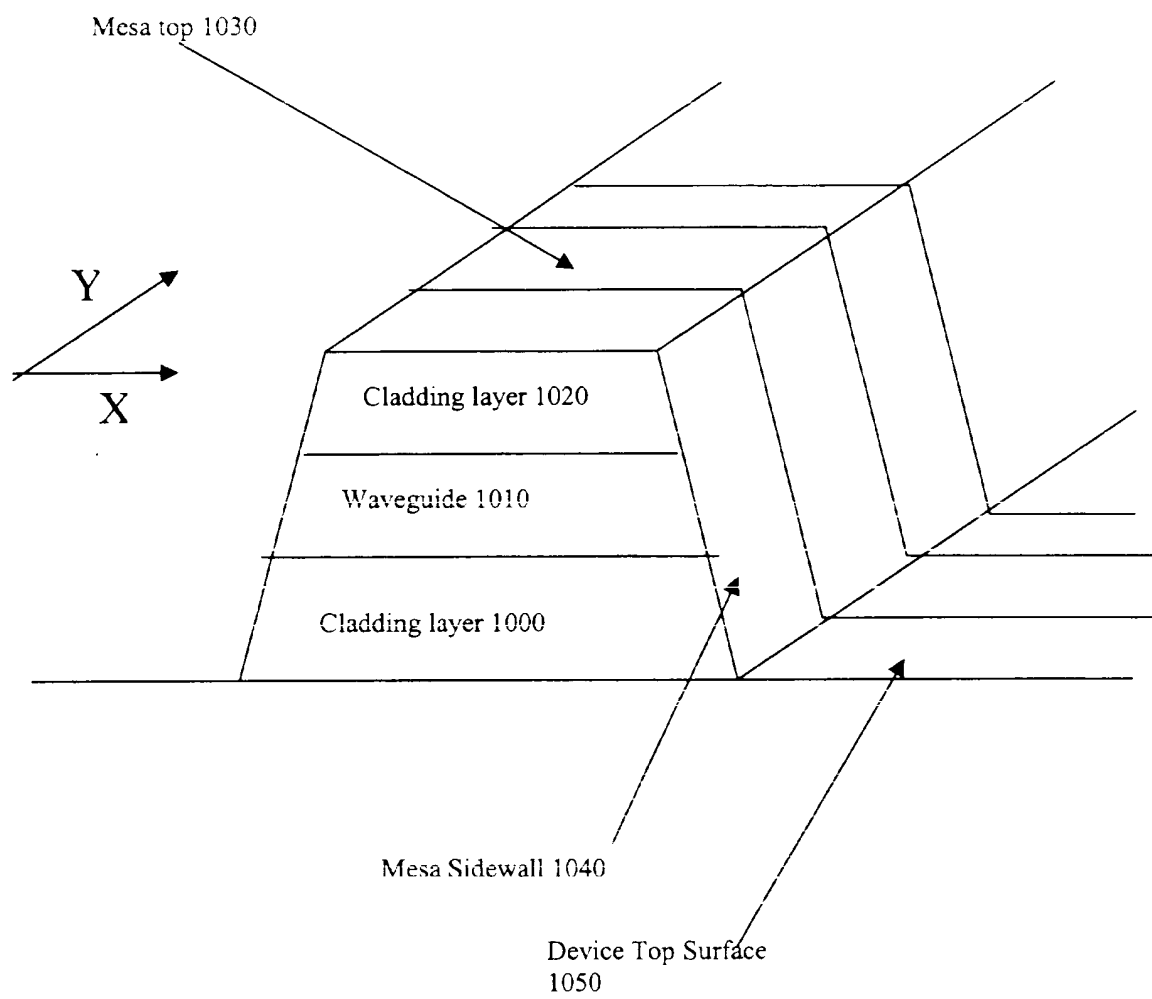


FIG. 22

Create a first cladding layer (Step 910).



Create a grating layer (Step 920).



Create a hole confinement region layer (Step 930).



Create an electron confinement region layer (Step 940).



Create a second cladding layer (Step 950).



(Optional) Pattern laser structure and additional device processing (Step 960).

FIG. 23